Micron Technology, Inc.
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Boise, ID United States

Product Change Notice

Micron PCN: 31591
Date: 6/11/2015

Type of Change:	Manufacturing Site Change, Product Material Change, Part Number Change
Title of Change:	50nm 288Mb and 576Mb RLDRAM (F66A/F67A) changing from µBGA to FBGA
Description of Change:	Micron is changing the package for 288Mb and 576Mb RLDRAM 2 devices. The µBGA package currently assembled by Shindo Electronics/FLEXEED is changing to an FBGA package assembled by Micron and by PTI. Note that the package dimensions and ball-out will remain the same. (Please see attachment for details.)
Reason for Change:	Supply Flexibility/Security

Contact Information:

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Product Affected: 50nm 288Mb and 576Mb RLDRAM 2 µBGA devices

Affected Micron Part Number	Suggested Replacement Part
288Mb RL2	
MT49H8M36BM-5:B	MT49H8M36SJ-5:B
MT49H8M36BM-33:B	MT49H8M36SJ-25:B
MT49H8M36FM-33:B	MT49H8M36SJ-25:B
MT49H8M36BM-25:B	MT49H8M36SJ-25:B
MT49H8M36FM-25:B	MT49H8M36SJ-25:B
MT49H8M36BM-25E:B	MT49H8M36SJ-25E:B
MT49H8M36BM-18:B	Contact Factory
MT49H8M36BM-TI:B	MT49H8M36SJ-TI:B
MT49H8M36BM-33 IT:B	MT49H8M36SJ-25 IT:B
MT49H8M36BM-25 IT:B	MT49H8M36SJ-25 IT:B
MT49H8M36FM-25 IT:B	MT49H8M36SJ-25 IT:B
MT49H16M18BM-5:B	MT49H16M18SJ-25:B
MT49H16M18BM-33:B	MT49H16M18SJ-25:B
MT49H16M18FM-33:B	MT49H16M18SJ-25:B
MT49H16M18BM-25:B	MT49H16M18SJ-25:B
MT49H16M18FM-25:B	MT49H16M18SJ-25:B
MT49H16M18BM-18:B	Contact Factory
MT49H16M18BM-25 IT:B	MT49H16M18SJ-25 IT:B
MT49H16M18FM-25 IT:B	MT49H16M18SJ-25 IT:B
MT49H16M18CFM-33:B	MT49H16M18CSJ-25:B
MT49H16M18CBM-25:B	MT49H16M18CSJ-25:B
MT49H16M18CFM-25:B	MT49H16M18CSJ-25:B
MT49H16M18CFM-25 IT:B	MT49H16M18CSJ-25 IT:B
MT49H16M18CBM-25 IT:B	MT49H16M18CSJ-25 IT:B
MT49H32M9BM-33:B	MT49H32M9SJ-25:B
MT49H32M9FM-33:B	MT49H32M9SJ-25:B
MT49H32M9BM-25:B	MT49H32M9SJ-25:B
MT49H32M9FM-25:B	MT49H32M9SJ-25:B

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576Mb RL2

MT49H16M36BM-33:B	MT49H16M36SJ-25:B
MT49H16M36BM-25:B	MT49H16M36SJ-25:B
MT49H16M36FM-25:B	MT49H16M36SJ-25:B
MT49H16M36BM-25E:B	MT49H16M36SJ-25E:B
MT49H16M36FM-25E:B	MT49H16M36SJ-25E:B
MT49H16M36BM-18:B	MT49H16M36SJ-18:B
MT49H16M36FM-18:B	MT49H16M36SJ-18:B
MT49H16M36BM-25 IT:B	MT49H16M36SJ-25 IT:B
MT49H16M36FM-25 IT:B	MT49H16M36SJ-25 IT:B
MT49H16M36BM-18 IT:B	MT49H16M36SJ-18 IT:B
MT49H32M18BM-33:B	MT49H32M18SJ-25:B
MT49H32M18FM-33:B	MT49H32M18SJ-25:B
MT49H32M18BM-25:B	MT49H32M18SJ-25E:B
MT49H32M18FM-25:B	MT49H32M18SJ-25:B
MT49H32M18BM-25E:B	MT49H32M18SJ-25E:B
MT49H32M18FM-25E:B	MT49H32M18SJ-25E:B
MT49H32M18BM-18:B	MT49H32M18SJ-18:B
MT49H32M18CBM-25:B	MT49H32M18CSJ-25E:B
MT49H32M18CFM-25:B	MT49H32M18CSJ-25E:B
MT49H32M18CBM-18:B	MT49H32M18CSJ-18:B
MT49H32M18CFM-18:B	MT49H32M18CSJ-18:B
MT49H32M18CBM-25 IT:B	MT49H32M18CSJ-25E IT:B
MT49H32M18CFM-25E:B	MT49H32M18CSJ-18:B
MT49H64M9BM-25:B	MT49H64M9SJ-25E:B
MT49H64M9FM-25:B	MT49H64M9SJ-25E:B
MT49H64M9FM-25E:B	MT49H64M9SJ-25E:B
MT49H64M9CBM-25E:B	Contact Factory
MT49H64M9BM-25E IT:B	Contact Factory

Method of Identification:

The package code in the marketing part number will change from BM/FM to SJ/TR:

Ex.

Discontinued µBGA Part Number	Replacement FBGA Part Number
MT49H8M36**BM**-25:B	MT49H8M36**SJ**-25:B

Micron Sites Affected: MTI - Micron Boise
Subcontractor

Product/Data Schedule

New/Changed Product:

Sample Availability: 15-Jul-2015

Qual Data Availability: 5-Jun-2015

Production Shipments: 15-Jul-2015

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Current/Discontinued Product:

Last Purchase Date*:	1/15/2016
Last Shipment Date:	7/15/2016

* Orders placed prior to the last purchase date are subject to current inventory levels, which may vary based on market conditions and customer demand. Early orders are encouraged.

RLDRAM2 50nm FBGA Package Solution

(F66A/F67A)

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FBGA X-Section

Description	144b FBGA
Package Type	FCIP with molded underfill
Package Thickness (C)	1.2
Package Body W x L	11.0 x 18.5mm
Solder Ball Pad Size	0.4mm, NSMD
1st Level Solder Ball Diameter	0.125mm (preform), SAC305
2nd Level Solder Ball Diameter	0.5mm (preform), SAC302
Die W x L	6.2 x 8.0mm
Die Thickness (D)	0.25
1st Level Stand-Off (E)	0.075
Substrate Layers	4
Substrate Thickness (B)	0.21
Surface Finish	ENEPIG
Mold Cap Thickness (A)	0.5

*Drawing is not to scale

** All dimensions are in mm

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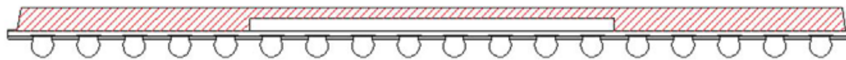
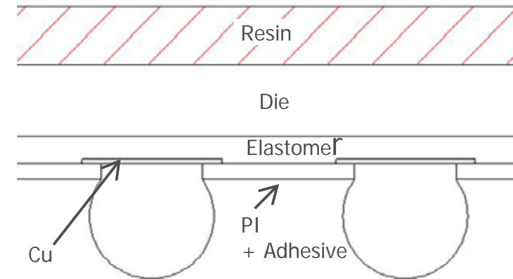
RLDRAM uBGA X-Section





Description	144b uBGA
Die W x L	6.2 x 8.0mm
Package Type	uBGA
Package Thickness	1.2mm
Package Body W x L	11.0 x 18.5
Solder Ball Diameter	0.5mm, SAC305
Die Thickness	0.280
Elastomer Thickness	0.110
Tab Tape Total Thickness	0.080
Mold Cap (Resin) Thickness	0.490

*Drawings are not to scale

** All dimensions are in mm

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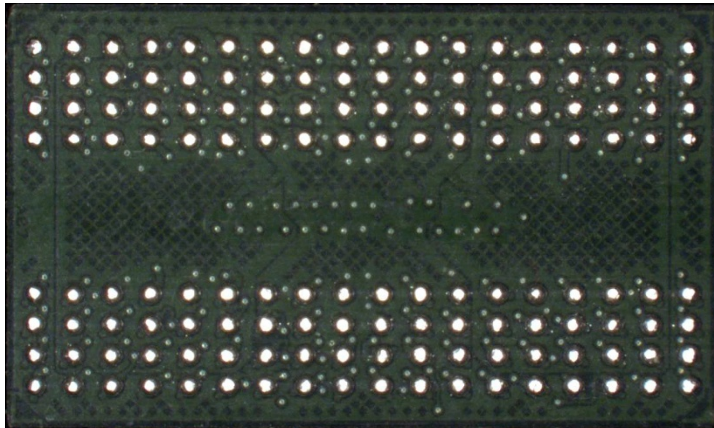
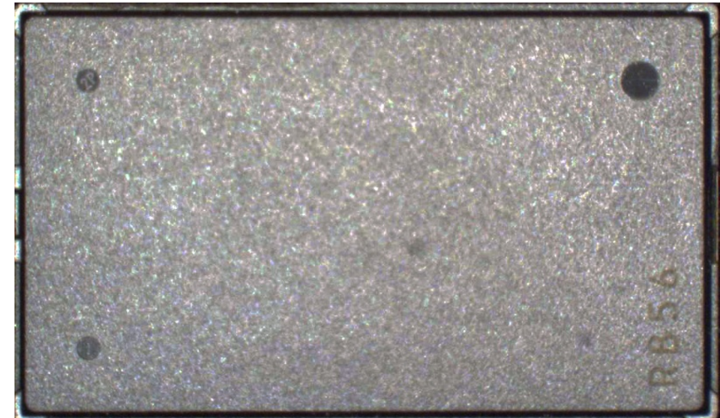
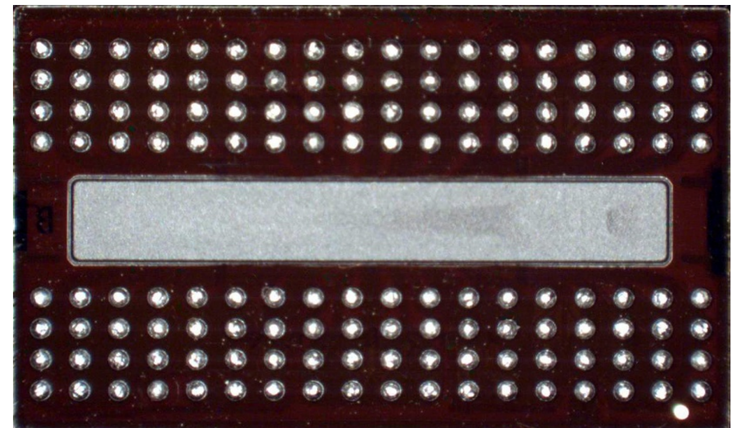
Package Image Comparison

FBGA



uBGA





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